The Spectra™ FOUP holds 300 mm wafers safely and securely while they are transported and transferred within the fab as they move through hundreds of sophisticated process steps. Designed to address not only particles but to also minimize and control VOC, oxygen, and relative humidity (RH), our FOUPs provide superior microenvironment control, optimum automation integration, and low cost of ownership.

Hydrophobic materials of construction with clean carbon loading are designed for low moisture, and low volatile absorption and desorption. Generous radii in part design and open wash slots in the FOUP door cover eliminate water or moisture traps, enabling effective cleaning and reducing drying cycle times.

These advanced FOUPs create a sealed wafer environment that provides static protection, white-light shielding, and offers a considerable positive impact on device yield.

**FEATURES & BENEFITS**

**Technology-enabling**
- Unsurpassed cleanability and dryability
- Effective grounding of the wafers through the door latch, conveyor plate, and top handle
- Optimized hydrophobic materials for wafer contact and microenvironment control
- Advanced purge options
  - Front/rear purge option available
  - Purge-diffusing snorkels for optimum purge gas dispersion
- ESD shell option for added wafer protection

**Interoperability**
- Industry-proven door for equipment interoperability and long life
- Wafer supports integral with shell to give excellent wafer plane performance and reliable wafer access
- Accurate equipment interfaces
  - Top robotic flange
  - Bottom kinematic coupling
  - Meets all applicable SEMI® standards

**SPECIFICATIONS**

<table>
<thead>
<tr>
<th>Dimensions</th>
<th>Width</th>
<th>416 mm (16.4”)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Depth</td>
<td>333 mm (13.1”)</td>
</tr>
<tr>
<td></td>
<td>Height</td>
<td>335 mm (13.2”)</td>
</tr>
<tr>
<td>Weight</td>
<td>Empty</td>
<td>4.2 kg (9.26 lb)</td>
</tr>
<tr>
<td></td>
<td>With wafers</td>
<td>7.3 kg (16.09 lb)</td>
</tr>
<tr>
<td>Wafer spacing</td>
<td>10 mm (0.39”)</td>
<td></td>
</tr>
<tr>
<td>Capacity</td>
<td>25 wafers</td>
<td></td>
</tr>
</tbody>
</table>

The Spectra™ FOUP, with advanced inert gas diffusion purge, protects wafers through hundreds of process steps.
MATERIALS OF CONSTRUCTION

- Ultrapure polycarbonate or barrier material used in the FOUP shell, door housing, and door panels
- Carbon-filled PEEK or barrier material used in wafer contact areas in the shell, door housing, and door components
- Thermoplastic elastomer (TPE) material used in the critical door seal
- Flame retardant material option available
- Humidity control barrier materials available to enable leading edge wafer processing technology

CONFIGURATION OPTIONS AND ACCESSORIES

Shell and Door Color Options
- Amber, red, green, clear, and black (ESD shell only)

Segregation Options
- Info pads configurable by customer

Identification Options
- Bar code and alphanumeric character labels
- Color handle inserts
- Cardholders
- RFID tags with read/write capability

FOR MORE INFORMATION

Please call your Regional Customer Service Center today to learn what Entegris can do for you. Visit entegris.com and select the Contact Us link to find the customer service center nearest you.

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